



## 12 Output Buffer for 2 DDR and 3 SDRAM DIMMS

- Space-saving 28-pin SSOP package

### Features

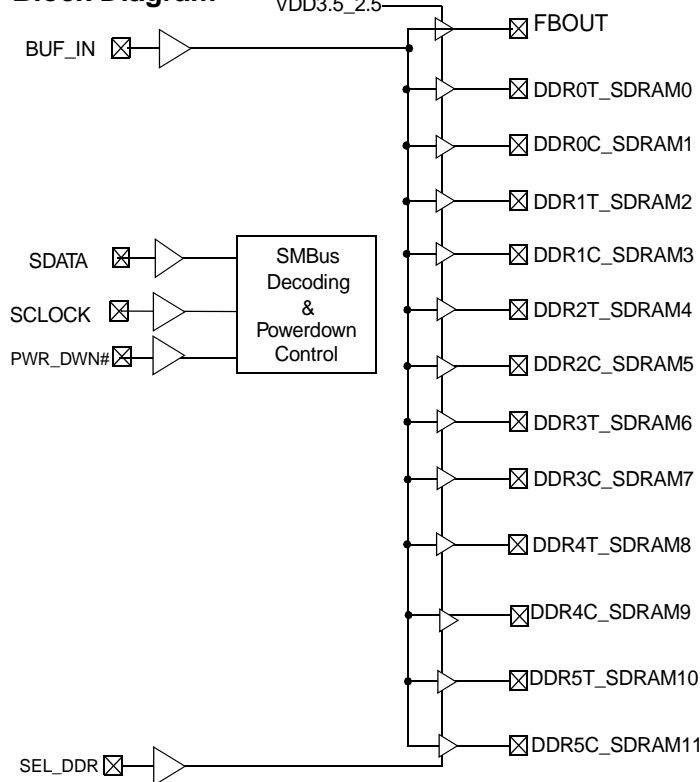
- One input to 12 output buffer/drivers
- Supports up to 2 DDR DIMMs or 3 SDRAM DIMMS
- One additional output for feedback
- SMBus interface for individual output control
- Low skew outputs (< 100 ps)
- Supports 266 MHz DDR SDRAM
- Dedicated pin for power management support

### Functional Description

The W256 is a 3.3V/2.5V buffer designed to distribute high-speed clocks in PC applications. The part has 12 outputs. Designers can configure these outputs to support 3 unbuffered standard SDRAM DIMMs and 2 DDR DIMMs. The W256 can be used in conjunction with the W250-02 or similar clock synthesizer for the VIA Pro 266 chipset.

The W256 also includes an SMBus interface which can enable or disable each output clock. On power-up, all output clocks are enabled (internal pull up).

### Block Diagram



### Pin Configuration<sup>[1]</sup>

#### SSOP Top View

FBOUT	1	28	SEL_DDR*
*PWR_DWN#	2	27	DDR5T_SDRAM10
DDR0T_SDRAM0	3	26	DDR5C_SDRAM11
DDR0C_SDRAM1	4	25	VDD3.3_2.5
VDD3.3_2.5	5	24	GND
GND	6	23	DDR4T_SDRAM8
DDR1T_SDRAM2	7	22	DDR4C_SDRAM9
DDR1C_SDRAM3	8	21	VDD3.3_2.5
VDD3.3_2.5	9	20	GND
BUF_IN	10	19	DDR3T_SDRAM6
GND	11	18	DDR3C_SDRAM7
DDR2T_SDRAM4	12	17	GND
DDR2C_SDRAM5	13	16	SCLK
VDD3.3_2.5	14	15	SDATA

#### Note:

1. Internal 100K pull-up resistors present on inputs marked with \*. Design should not rely solely on internal pull-up resistor to set I/O pins HIGH.

**Pin Summary**

Name	Pins	Description
SEL_DDR	28	<p>Input to configure for DDR-ONLY mode or STANDARD SDRAM mode. 1 = DDR-ONLY mode. 0 = STANDARD SDRAM mode.</p> <p>When SEL_DDR is pulled high or configured for DDR-ONLY mode, all the buffers will be configured as DDR outputs.</p> <p>Connect VDD3.3_2.5 to a 2.5V power supply in DDR-ONLY mode.</p> <p>When SEL_DDR is pulled LOW or configured for STANDARD SDRAM output, all the buffers will be configured as STANDARD SDRAM outputs.</p> <p>Connect VDD3.3_2.5 to a 3.3V power supply in STANDARD SDRAM mode.</p>
SCLK	16	SMBus clock input
SDATA	15	SMBus data input
BUF_IN	10	Reference input from chipset. 2.5V input for DDR-ONLY mode; 3.3V input for STANDARD SDRAM mode.
FBOUT	1	Feedback clock for chipset. Output voltage depends on VDD3.3_2.5V.
PWR_DWN#	2	Active LOW input to enable Power Down mode; all outputs will be pulled LOW.
DDR[0:5]T_SDRAM [0,2,4,6,8,10]	3, 7, 12, 19, 23, 27	Clock outputs. These outputs provide copies of BUF_IN. Voltage swing depends on VDD3.3_2.5 power supply.
DDR[0:5]C_SDRAM [1,3,5,7,9, 11]	4, 8, 13, 18, 22, 26	Clock outputs. These outputs provide complementary copies of BUF_IN when SEL_DDR is active. These outputs provide copies of BUF_IN when SEL_DDR is inactive. Voltage swing depends on VDD3.3_2.5 power supply.
VDD3.3_2.5	5, 9, 14, 21, 25	Connect to 2.5V power supply when W256 is configured for DDR-ONLY mode. Connect to 3.3V power supply, when W256 is configured for standard SDRAM mode.
GND	6, 11, 17, 20, 24	Ground

## Serial Configuration Map

- The Serial bits will be read by the clock driver in the following order:

Byte 0 - Bits 7, 6, 5, 4, 3, 2, 1, 0

Byte 1 - Bits 7, 6, 5, 4, 3, 2, 1, 0

.

Byte N - Bits 7, 6, 5, 4, 3, 2, 1, 0

- Reserved and unused bits should be programmed to "0".
- SMBus Address for the W256 is:

A6	A5	A4	A3	A2	A1	A0	R/W
1	1	0	1	0	0	1	----

## Byte 6: Outputs Active/Inactive Register (1 = Active, 0 = Inactive), Default = Active

Bit	Pin #	Description	Default
Bit 7	--	Reserved, drive to 0	0
Bit 6	--	Reserved, drive to 0	0
Bit 5	--	Reserved, drive to 0	0
Bit 4	1	FBOUT	1
Bit 3	27, 26	DDR5T_SDRAM10, DDR5C_SDRAM11	1
Bit 2	--	Reserved, drive to 0	1

## Byte 6: Outputs Active/Inactive Register (1 = Active, 0 = Inactive), Default = Active

Bit 1	23, 22	DDR4T_SDRAM8, DDR4C_SDRAM9	1
Bit 0	--	Reserved, drive to 0	1

## Byte 7: Outputs Active/Inactive Register (1 = Active, 0 = Inactive), Default = Active

Bit	Pin #	Description	Default
Bit 7	--	Reserved, drive to 0	1
Bit 6	19, 18	DDR3T_SDRAM6, DDR3C_SDRAM7	1
Bit 5	12, 13	DDR2T_SDRAM4, DDR2C_SDRAM5	1
Bit 4	--	Reserved, drive to 0	1
Bit 3	--	Reserved, drive to 0	1
Bit 2	7, 8	DDR1T_SDRAM2, DDR1C_SDRAM3	1
Bit 1	--	Reserved, drive to 0	1
Bit 0	3, 4	DDR0T_SDRAM0, DDR0C_SDRAM1	1

**Maximum Ratings**

Supply Voltage to Ground Potential ..... -0.5 to +7.0V  
 DC Input Voltage (except BUF\_IN) ..... -0.5V to  $V_{DD}+0.5$

Storage Temperature ..... -65°C to +150°C  
 Static Discharge Voltage ..... >2000V  
 (per MIL-STD-883, Method 3015)

**Operating Conditions**

Parameter	Description	Min.	Typ.	Max.	Unit
VDD3.3	Supply Voltage	3.135		3.465	V
VDD2.5	Supply Voltage	2.375		2.625	V
T <sub>A</sub>	Operating Temperature (Ambient Temperature)	0		70	°C
C <sub>OUT</sub>	Output Capacitance		6		pF
C <sub>IN</sub>	Input Capacitance		5		pF

**Electrical Characteristics** Over the Operating Range

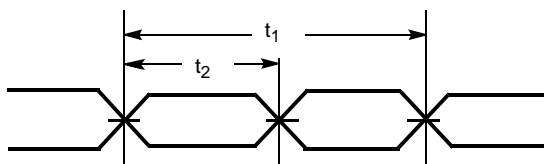
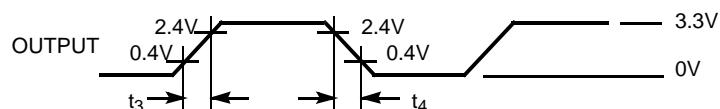
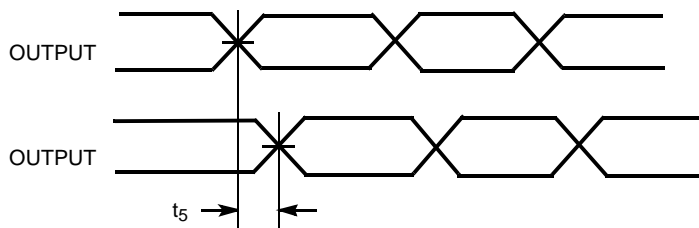
Parameter	Description	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>IL</sub>	Input LOW Voltage	For all pins except SMBus			0.8	V
V <sub>IH</sub>	Input HIGH Voltage		2.0			V
I <sub>IL</sub>	Input LOW Current	V <sub>IN</sub> = 0V			50	μA
I <sub>IH</sub>	Input HIGH Current	V <sub>IN</sub> = V <sub>DD</sub>			50	μA
I <sub>OH</sub>	Output HIGH Current	VDD = 2.375V V <sub>OUT</sub> = 1V	-18	-32		mA
I <sub>OL</sub>	Output LOW Current	VDD = 2.375V V <sub>OUT</sub> = 1.2V	26	35		mA
V <sub>OL</sub>	Output LOW Voltage <sup>[2]</sup>	I <sub>OL</sub> = 12 mA, VDD = 2.375V			0.6	V
V <sub>OH</sub>	Output HIGH Voltage <sup>[2]</sup>	I <sub>OH</sub> = -12 mA, VDD = 2.375V	1.7			V
I <sub>DD</sub>	Supply Current <sup>[2]</sup> (DDR-Only mode)	Unloaded outputs, 133 MHz			400	mA
I <sub>DD</sub>	Supply Current (DDR-Only mode)	Loaded outputs, 133 MHz			500	mA
I <sub>DDS</sub>	Supply Current	PWR_DWN# = 0			100	μA
V <sub>OUT</sub>	Output Voltage Swing	See Test Circuitry (Refer to Figure 1)	0.7		VDD +0.6	V
V <sub>OC</sub>	Output Crossing Voltage		(VDD/2) -0.1	VDD/2	(VDD/2) +0.1	V
IN <sub>DC</sub>	Input Clock Duty Cycle		48		52	%

**Notes:**

2. Parameter is guaranteed by design and characterization. Not 100% tested in production.

**Switching Characteristics** <sup>[Figure 3]</sup>

Parameter	Name	Test Conditions	Min.	Typ.	Max.	Unit
--	Operating Frequency		66		133	MHz
--	Duty Cycle <sup>[2,4]</sup> = $t_2 \div t_1$	Measured at 1.4V for 3.3V outputs Measured at VDD/2 for 2.5V outputs.	$I_{NDC}$ -5%		$I_{NDC}$ +5%	%
$t_3$	SDRAM Rising Edge Rate <sup>[2]</sup>	Measured between 0.4V and 2.4V	1.0		2.50	V/ns
$t_4$	SDRAM Falling Edge Rate <sup>[2]</sup>	Measured between 2.4V and 0.4V	1.0		2.50	V/ns
$t_{3d}$	DDR Rising Edge Rate <sup>[2]</sup>	Measured between 20% to 80% of output (Refer to <i>Figure 1</i> )	0.5		1.50	V/ns
$t_{4d}$	DDR Falling Edge Rate <sup>[2]</sup>	Measured between 20% to 80% of output (Refer to <i>Figure 1</i> )	0.5		1.50	V/ns
$t_5$	Output to Output Skew <sup>[2]</sup>	All outputs equally loaded			100	ps
$t_6$	SDRAM Buffer HH Prop. Delay <sup>[2]</sup>	Input edge greater than 1 V/ns	5		10	ns
$t_7$	SDRAM Buffer LLProp. Delay <sup>[2]</sup>	Input edge greater than 1 V/ns	5		10	ns
$t_8$	SDRAM Buffer LLProp. Delay <sup>[2]</sup>	Input edge greater than 1 V/ns	5		10	ns

**Switching Waveforms**
**Duty Cycle Timing**

**All Outputs Rise/Fall Time**

**Output-Output Skew**

**Notes:**

3. All parameters specified with loaded outputs.
4. Duty cycle of input clock is 50%. Rising and falling edge rate is greater than 1V/ns.

**Switching Waveforms** (continued)

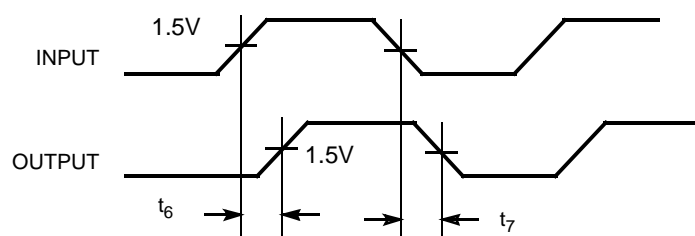
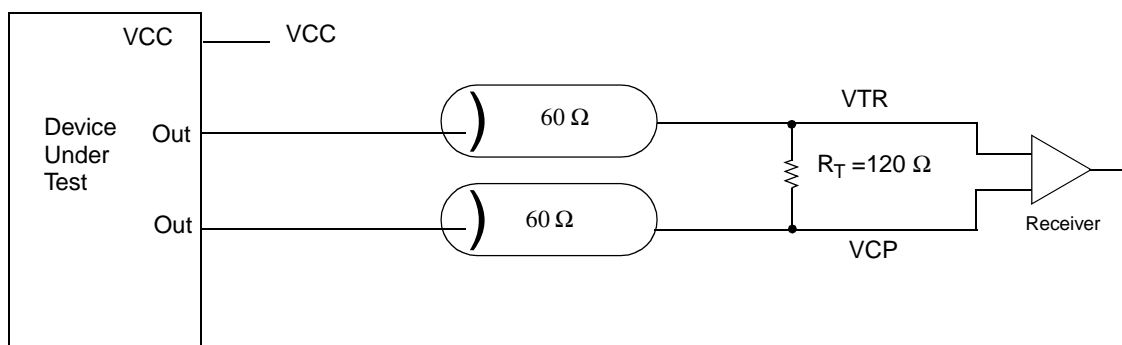
**SDRAM Buffer HH and LL Propagation Delay**


Figure 1 shows the differential clock directly terminated by a 120  $\Omega$  resistor



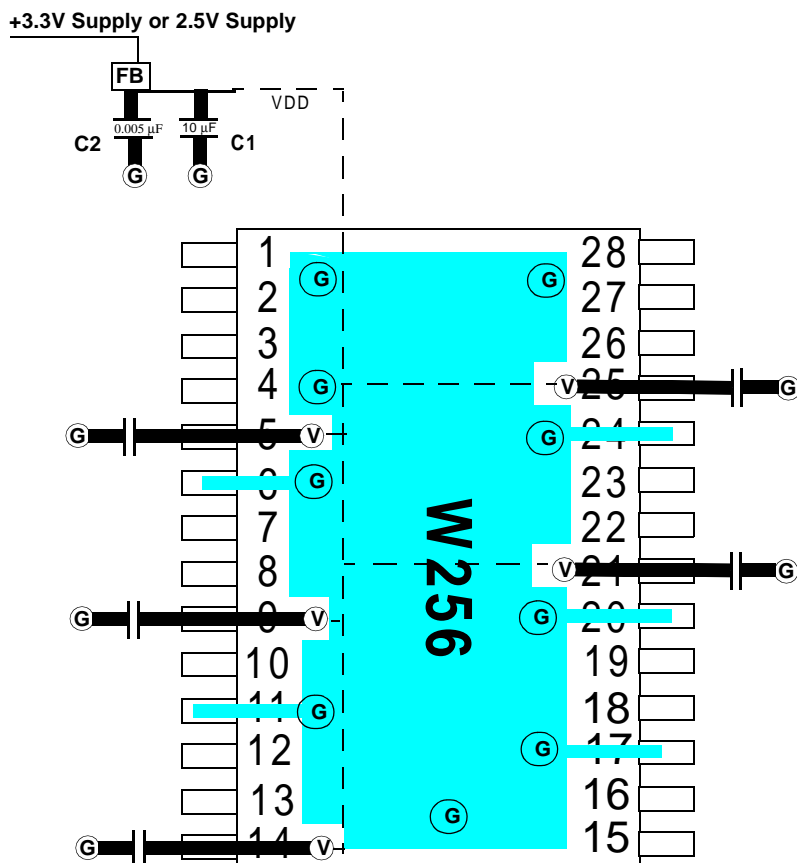
**Figure 1. Differential Signal Using Direct Termination Resistor.**

**Ordering Information**

Ordering Code	Package Type	Operating Range
W256	28-pin SSOP	Commercial

Document #: 38-01083-\*A

# Layout Example Single Voltage



FB = Dale ILB1206 - 300 (300 $\Omega$  @ 100 MHz)

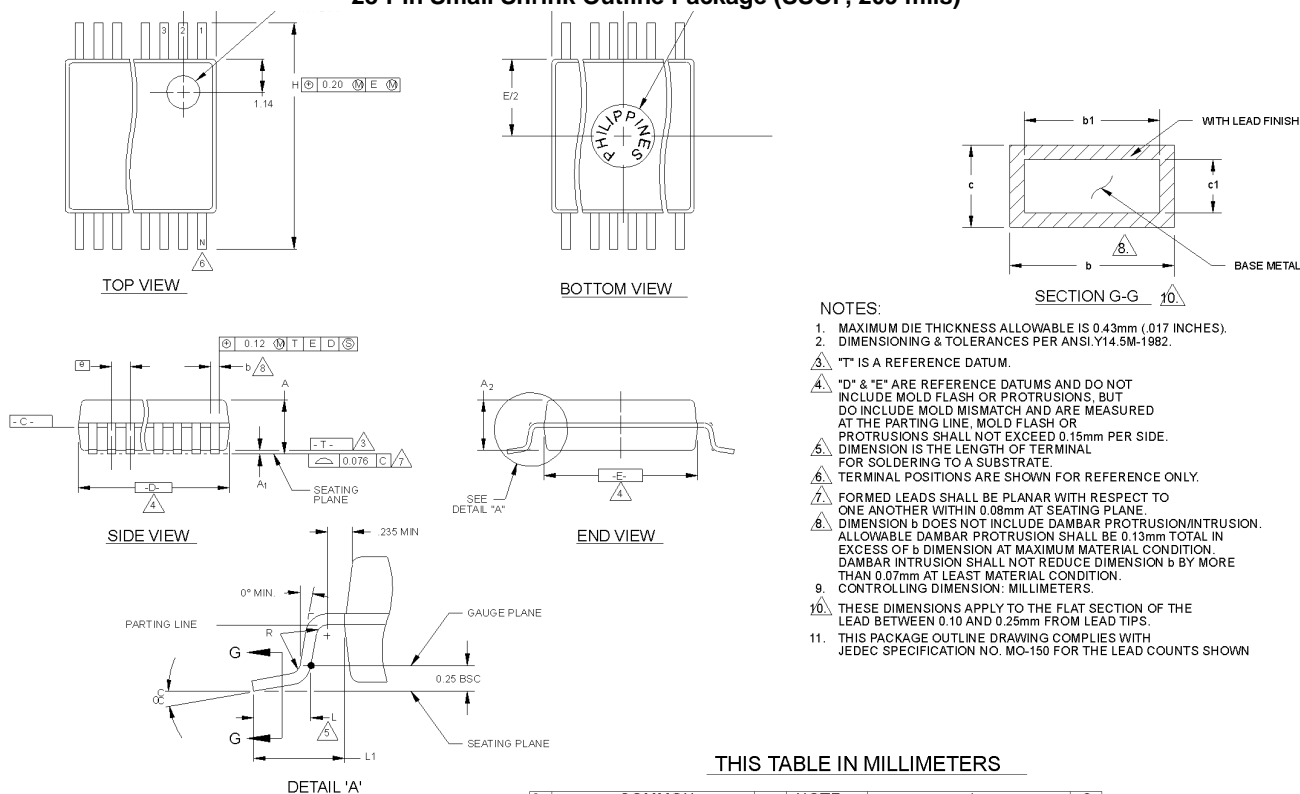
Ceramic Caps C1 = 10 – 22  $\mu\text{F}$  C2 = .005  $\mu\text{F}$

ⓐ = VIA to GND plane layer ⓑ = VIA to respective supply plane layer

Note: Each supply plane or strip should have a ferrite bead and capacitors  
All bypass caps = 0.1  $\mu\text{F}$  ceramic

# Mechanical Package Outline

## 28-Pin Small Shrink Outline Package (SSOP, 209 mils)



THIS TABLE IN MILLIMETERS

SYMBOL	COMMON DIMENSIONS			NOTE VARIATIONS	4 D			6 N
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.	
A	1.73	1.86	1.99	AA	6.07	6.20	6.33	14
A <sub>1</sub>	0.05	0.13	0.21	AB	6.07	6.20	6.33	16
A <sub>2</sub>	1.68	1.73	1.78	AC	7.07	7.20	7.33	20
b	0.25	-	0.38	AD	8.07	8.20	8.33	24
b <sub>1</sub>	0.25	0.30	0.33	AE	10.07	10.20	10.33	28
c	0.09	-	0.20	AF	10.07	10.20	10.33	30
c <sub>1</sub>	0.09	0.15	0.16					
D	SEE VARIATIONS							
E	5.20	5.30	5.38					
e	0.65 BSC							
H	7.65	7.80	7.90					
L	0.63	0.75	0.95					
L <sub>1</sub>	1.25 REF.							
N	SEE VARIATIONS							
α	0°	4°	8°					
R	0.09	0.15						

VARIATION AF  
IS DESIGNED BUT NOT TOOLED

THIS TABLE IN INCHES

SYMBOL	COMMON DIMENSIONS			NOTE VARIATIONS	4 D			6 N
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.	
A	.068	.073	.078	AA	.239	.244	.249	14
A <sub>1</sub>	.002	.005	.008	AB	.239	.244	.249	16
A <sub>2</sub>	.066	.068	.070	AC	.278	.284	.289	20
b	.010	-	.015	AD	.318	.323	.328	24
b <sub>1</sub>	.010	.012	.013	AE	.397	.402	.407	28
c	.004	-	.008	AF	.397	.402	.407	30
c <sub>1</sub>	.004	.006	.006					
D	SEE VARIATIONS							
E	.205	.209	.212					
e	.0256 BSC							
H	.301	.307	.311					
L	.025	.030	.037					
L <sub>1</sub>	.049 REF.							
N	SEE VARIATIONS							
α	0°	4°	8°					
R	.004	.006						